Absolute Maximum Ratings (Ta = 25°C)

	Characteristic	Symbol	Rating	Unit	
	Forward current	lF	50	mA	
	Forward current derating (Ta ≥ 53	ΔI _F / °C	-0.7	mA / °C	
	Peak forward current (100µs pulse	e, 100pps)	IFP	1	A
LED	Reverse voltage		VR	5	V
	Diode power dissipation		P_D	100	mW
	Diode power dissipation derating (ΔP _D /°C	-1.4	mW/°C	
	Junction temperature	Tj	125	(Vc)	
	Off-state output terminal voltage	VDRM	600	V	
	On-state RMS current	Ta=25°C	1	100	
		Ta=70°C	IT(RMS)	50	─mA
L	On-state current derating(Ta ≥ 25	ΔI _T / °C	-11	mA / °C	
Detector	Peak on-state current (100µs puls	ITP	(7/2)	A	
Det	Peak non-repetitive surge current (Pw=10ms)	ITSM (1.2	A	
	Output power dissipation		Po	300	mW
	Output power dissipation derating	ΔP _o /°C	-3.0	mW / °C	
	Junction temperature	Ţį	115	7,0	
Stora	age temperature range	1	T _{stg}	-55 to 125	°c
Oper	rating temperature range		Topr	-40 to 100	°C
Lead soldering temperature (10 s)			T _{sol}	260	°C
Isola	tion voltage (AC, 60 s, R.H. ≤ 60 %)	BVs	2500	V _{rms}

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Recommended Operating Conditions

Characteristic	Symbol	Min	Тур.	Max	Unit
Supply voltage	V _{AC}	_	_	240	Vac
Forward current	lF	15	20	25	mA
Peak on-state current	ITP	_	_	1	Α
Operating temperature	T _{opr}	-25	_	85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

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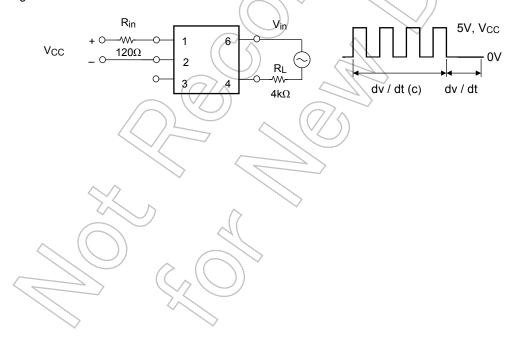
Electrical Characteristics (Ta = 25°C)

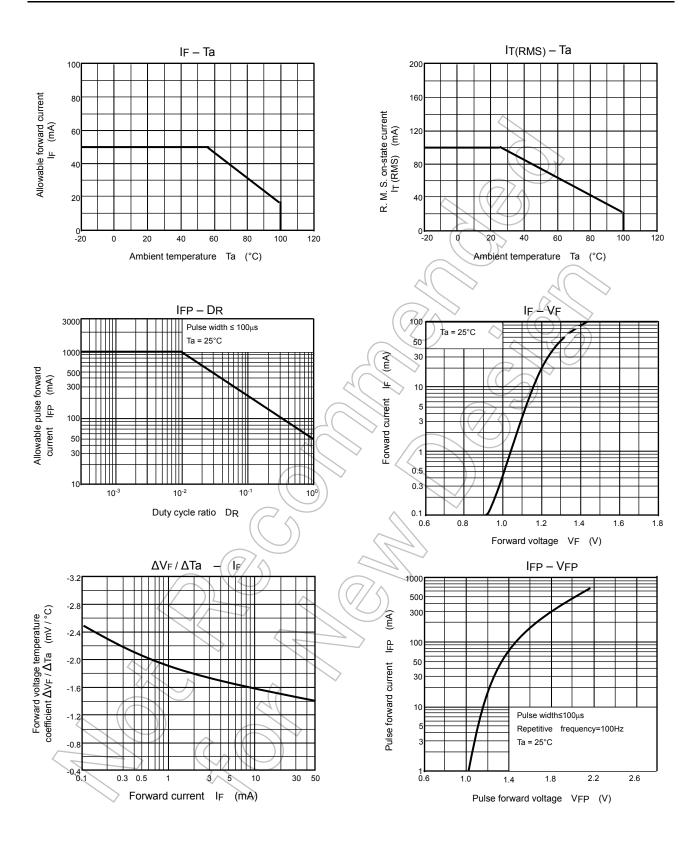
	Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
CED	Forward voltage	VF	I _F =10 mA	1.0	1.15	1.3	V
	Reverse current	I _R	V _R =5 V	_	_	10	μΑ
	Capacitance	Ст	VF=0 V, f=1 MHz	<u> </u>	30	_	pF
Detector	Peak off-state current	IDRM	V _{DRM} =600 V		10	1000	nA
	Peak on-state voltage	VTM	I _{TM} =100 mA		1.7	3.0	V
	Holding current	lΗ	0) \)	1.0	_	mA
	Critical rate of rise of off–state voltage	dv / dt	V _{in} =240 V _{rms} , Ta=85 °C (fig.1)))	500	_	V / µs
	Critical rate of rise of commutating voltage	dv / dt(c)	V _{in} =60 V _{rms} , I _T =15 mA (fig.1)	_	0.2	_	V / µs

Coupled Electrical Characteristics (Ta = 25°C)

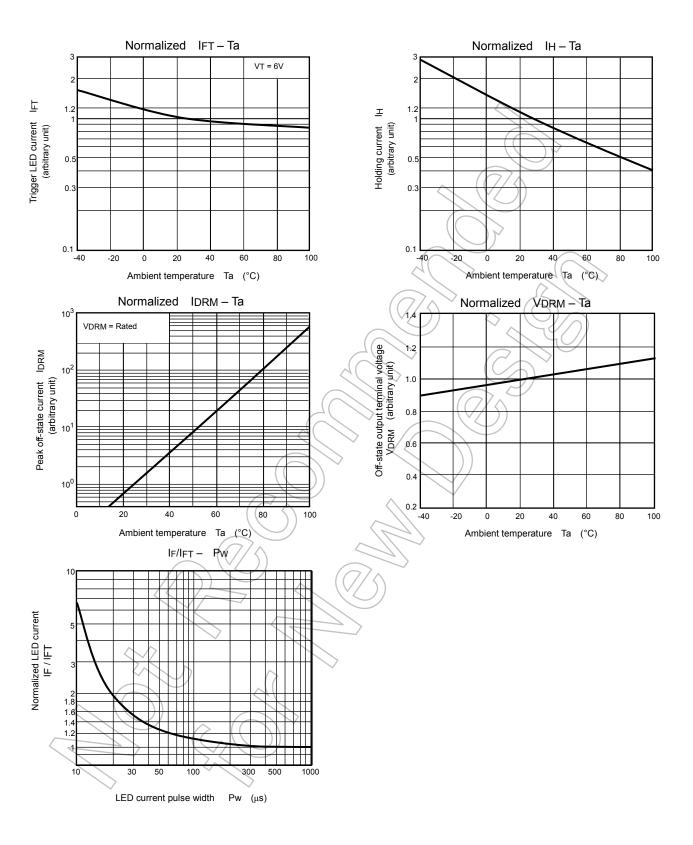
		//3/: \			>	
Characteristic	Symbol	Test Condition	Min	тур.	Max	Unit
Trigger LED current	l _{FT}	V _T =6 V, R _L =100 Ω		5	10	mA
Capacitance (input to output)	Cs	Vs=0 V, f=1 MHz		0.8	1	pF
Isolation resistance	Rs (V _S =500 V, R.H. ≤ 60 %	5×10 ¹⁰	10 ¹⁴		Ω
Isolation voltage	BVs	AC, 60 s	2500	_	-	V _{rms}

Fig.1: dv / dt test circuit





NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



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